



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  *: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-08-10
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMG Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STP16CPC26TTR	MBYB*UA42AD5	A	ZY1A	2016-08-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	88.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.4 x 7.8 x 1	24	gull wing	
Comment	TSSOP 24 BODY 4.40 0.65			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20 June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MBYB*UA42AD5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1.13	mg	supplier	die	Silicon (Si)	7440-21-3		1.08	mg	955752	12273
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	9735	125
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.009	mg	7965	102
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.002	mg	1770	23
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.019	mg	16814	216
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.006	mg	5310	68
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.003	mg	2655	34
Leadframe	Copper & its alloys	22.747	mg	supplier	alloy	Copper (Cu)	7440-50-8		22.03	mg	968479	250341
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.518	mg	22772	5886
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.031	mg	1363	352
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.027	mg	1187	307
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.141	mg	6199	1602
Die attach	Other inorganic materials	0.393	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.314	mg	798982	3568
Die attach				supplier	glue or tape	Bisphenol F type epoxy resin	9003-36-5		0.031	mg	78880	352
Die attach				supplier	glue or tape	Epoxy resin	68475-94-5		0.012	mg	30534	136
Die attach				supplier	glue or tape	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.012	mg	30534	136
Die attach				supplier	glue or tape	Gamma Butyrolactone	96-48-0		0.012	mg	30534	136
Die attach				supplier	glue or tape	Polyoxypropylenediamine	9046-10-0		0.012	mg	30534	136
Bonding wire	Other inorganic materials	0.681	mg	supplier	wire	Gold (Au)	7440-57-5		0.681	mg	1000000	7739
encapsulation	Other Organic Materials	61.947	mg	supplier	mold compound	Epoxy Resin	25068-38-6		4.646	mg	75000	52795
encapsulation				supplier	mold compound	Phenol Resin	29690-82-2		3.098	mg	50010	35205
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		53.646	mg	865998	609614
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.309	mg	4988	3511
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.248	mg	4003	2818
connections coating	Solder	1.102	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.102	mg	1000000	12523